

A2GR12N650MD02

650V N-Channel MOSFET



Features

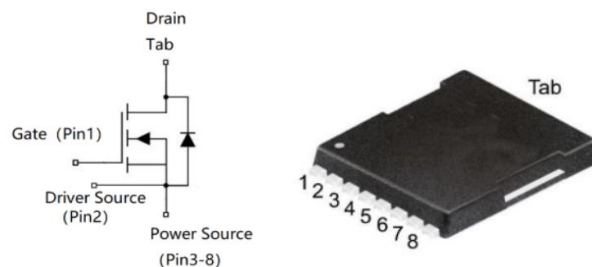
- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low $R_{DS(on)}$
- Optimized package with separate driver source pin
- Easy to parallel and simple to drive
- ROHS Compliant, Halogen free

Application

- EV motor drive
- DC/DC Converters
- Switch Mode Power Supplies
- Solar inverters
- EV charging

V_{DS}	650V
I_D	150A

Product Summary



Ordering Information

Part Number	Marking	Package	Packaging
A2GR12N650MD02	A2GR12N650MD02	TOLL	Reel

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage	650	V
I_D	Drain Current (continuous) at $T_c=25^\circ\text{C}$	150	A
I_D	Drain Current (continuous) at $T_c=100^\circ\text{C}$	100	A
I_{DM}	Drain Current (pulsed)	300	A
V_{GS}	Gate-Source Voltage	-10/+22	V
P_D	Power Dissipation $T_c=25^\circ\text{C}$	428	W
T_J, T_{stg}	Junction and Storage Temperature Range	-55 to +175	$^\circ\text{C}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Typical Performance-Static

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{DS}	Drain-source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	350			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=650\text{V}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$			100	μA
I_{GSS}	Gate-body Leakage Current	$V_{DS}=0\text{V}, V_{GS}=-10\text{ to }20\text{V}$			250	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=22\text{mA}$	2	3	4	V
$V_{GS(on)}$	Recommended turn-on Voltage	Static		18		V
$V_{GS(off)}$	Recommended turn-off Voltage			-5		V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS}=18\text{V}, I_D=75\text{A}$		12	20	$\text{m}\Omega$
		$V_{GS}=18\text{V}, I_D=75\text{A}, T_J=175^\circ\text{C}$		16		$\text{m}\Omega$

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Typical Performance-Dynamic

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
C _{iss}	Input Capacitance	V _{DS} =400V, f=1MHz V _{AC} =25mV		7160		pF
C _{oss}	Output Capacitance			325		pF
C _{rss}	Reverse Transfer Capacitance			31		pF
g _{fs}	Transconductance	V _{DS} =20V, I _D =15A		42		S
E _{oss}	C _{oss} Stored Energy	V _{DS} =400V, f=100kHz		32		uJ
E _{on}	Turn-On Energy (Body Diode)	V _{DS} =400V V _{GS} =-5/20V, I _D =50A L=60uH, T _J =175°C		426		uJ
E _{off}	Turn-Off Energy (Body Diode)			282		uJ
Q _g	Total Gate Charge	V _{DS} =400V		236		nC
Q _{gs}	Gate-source Charge	V _{GS} =-5/20V		56		nC
Q _{gd}	Gate-Drain Charge	I _D =50A		64		nC
R _{G(int)}	Internal Gate Resistance	f=1MHz, V _{AC} =25mV		2.2		Ω
t _{d(on)}	Turn-on Delay Time	V _{DS} =400V V _{GS} =-5/20V, I _D =50A L=60uH, R _{ext} =5Ω		25		ns
t _r	Rise Time			34		ns
t _{d(off)}	Turn-off Delay Time			62		ns
t _f	Fall Time			16		ns

Typical Performance-Reverse Diode (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{FSD}	Forward Voltage	V _{GS} =0V, I _F =50A, T _J =25°C		3.5	6	V
		V _{GS} =0V, I _F =50A, T _J =175°C		3	6	V
I _S	Continuous Diode Forward Current	V _{GS} =0V, T _C =25°C		80		A
t _{rr}	Reverse Recovery Time	V _{GS} =-5V, I _F =50A V _R =400V di/dt=2400A/μs, T _J =175°C		88		ns
Q _{rr}	Reverse Recovery Charge			680		nC
I _{rrm}	Peak Reverse Recovery Current			17		A

Thermal Characteristics

Symbol	Parameter	Value	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	0.35	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	40	°C/W

The values are based on the junction-to case thermal impedance which is measured with the device mounted to a large heat sink assuming maximum junction temperature of T_J(max)=175°C.

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Electrical Characteristics

Fig1. Output characteristics ($T_J = 25^\circ\text{C}$)

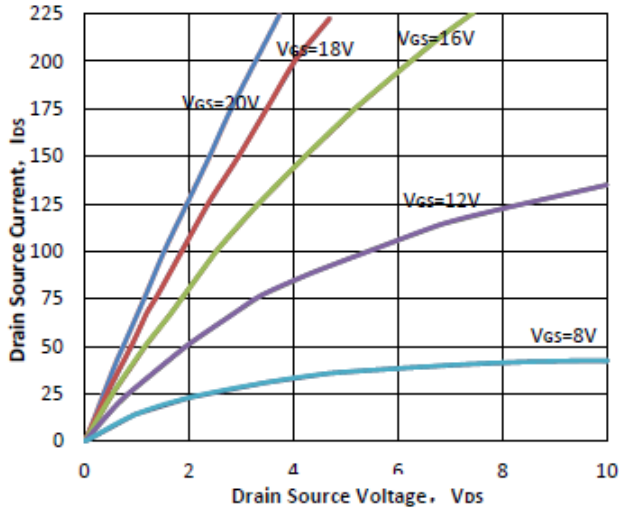


Fig2. Output characteristics ($T_J = 175^\circ\text{C}$)

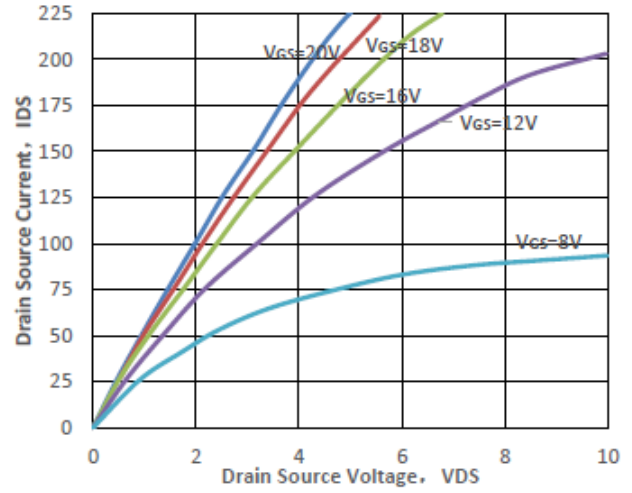


Fig3. Normalized On-Resistance vs. Temperature

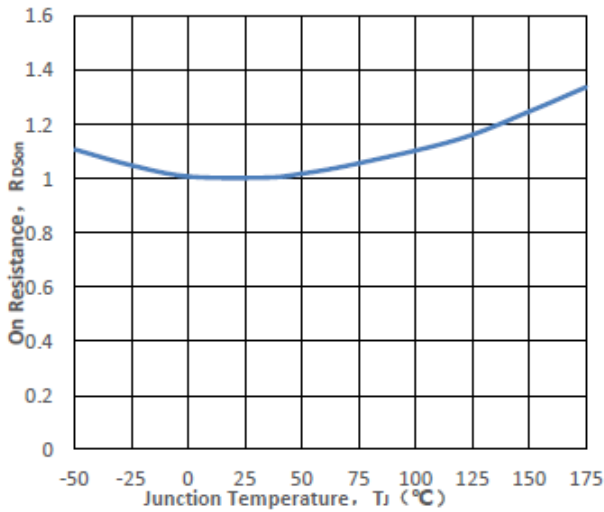


Fig4. On-Resistance vs. Temperature

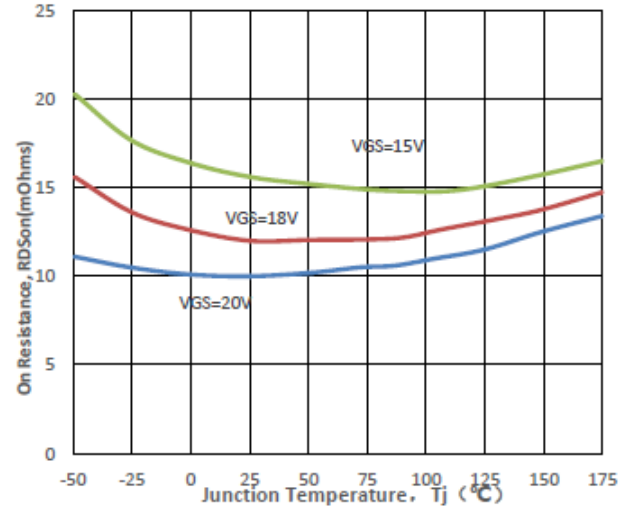


Fig5. Transfer Characteristic

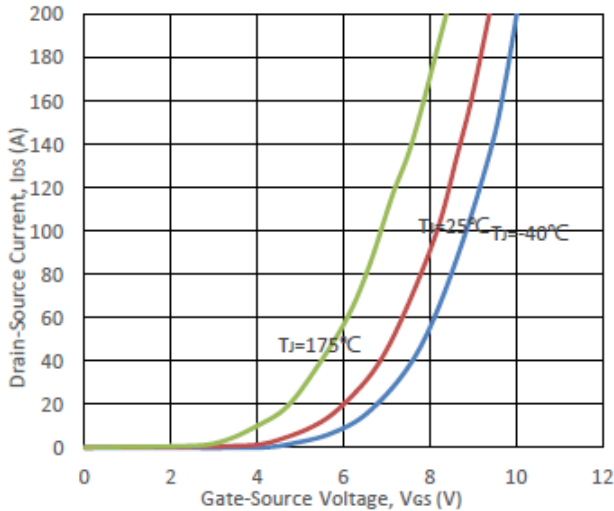
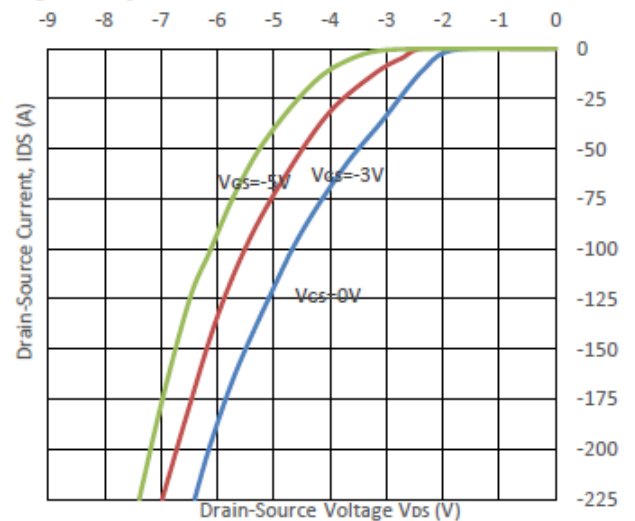


Fig6. Body Diode Characteristic at 25°C



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Fig7. Threshold Voltage vs. Temperature

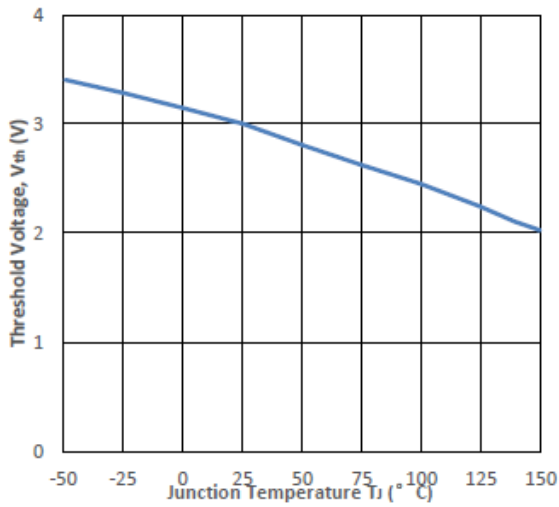


Fig8. Gate Charge Characteristics

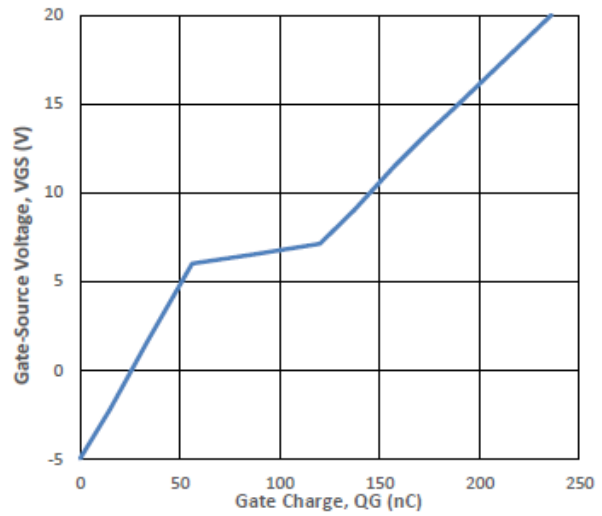


Fig9. 3rd Quadrant Characteristic at 25 °C

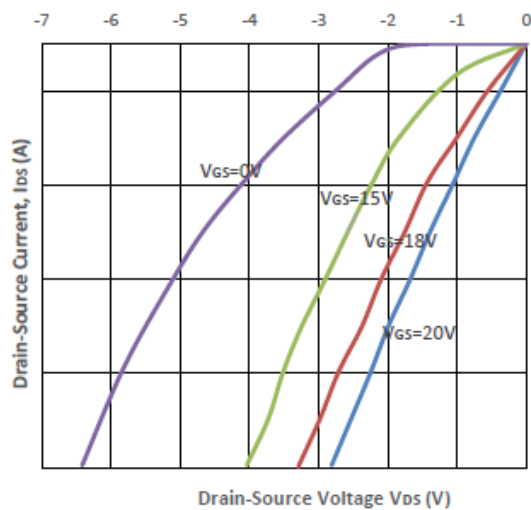


Fig10. Output Capacitor Stored Energy

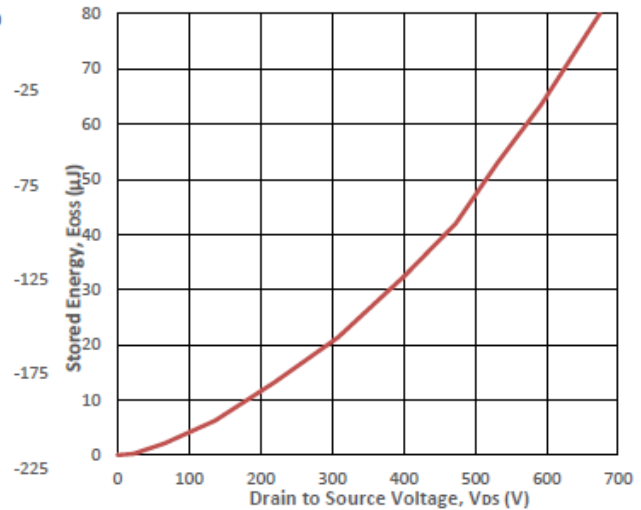


Fig11. Capacitances vs. Drain-Source

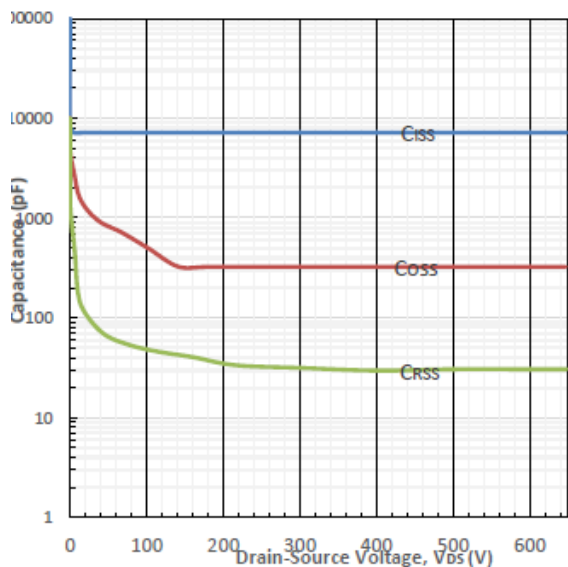
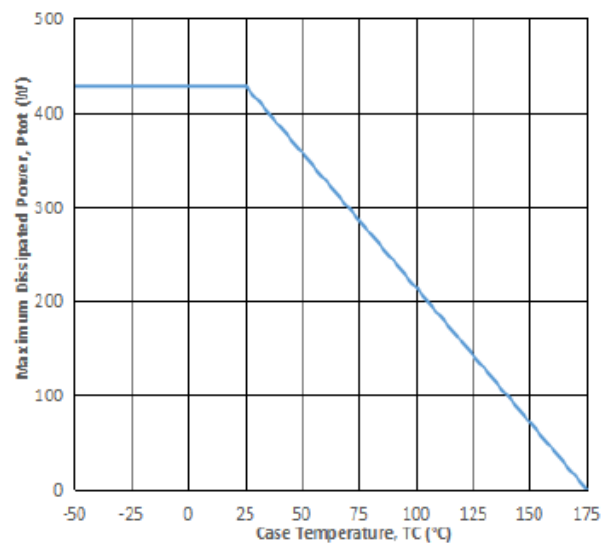


Fig12. Max Power Dissipation Derating Vs Tc



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Fig13. Switching Energy vs. Drain Current

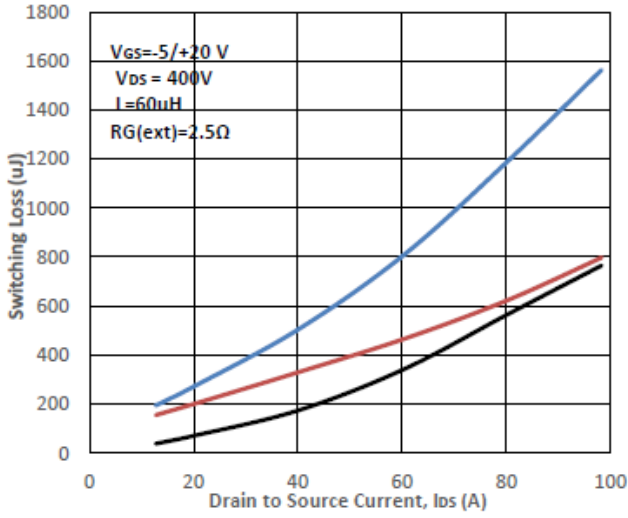


Fig14. Switching Energy vs. RG(ext)

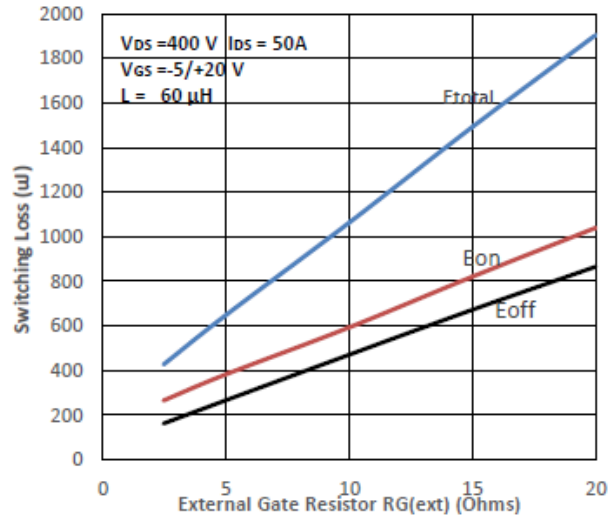


Fig15. Switching Energy vs. Temperature

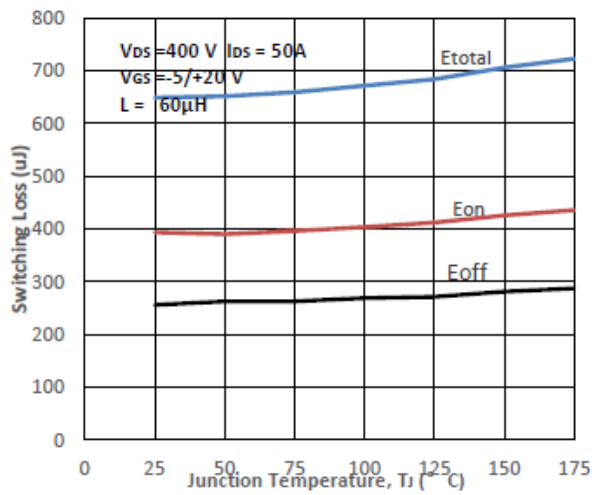


Fig16. Switching Times vs. RG(ext)

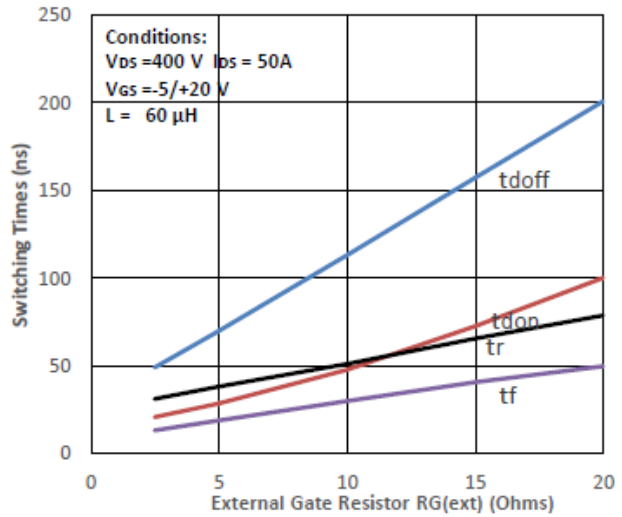


Fig17. Transient Thermal Impedance

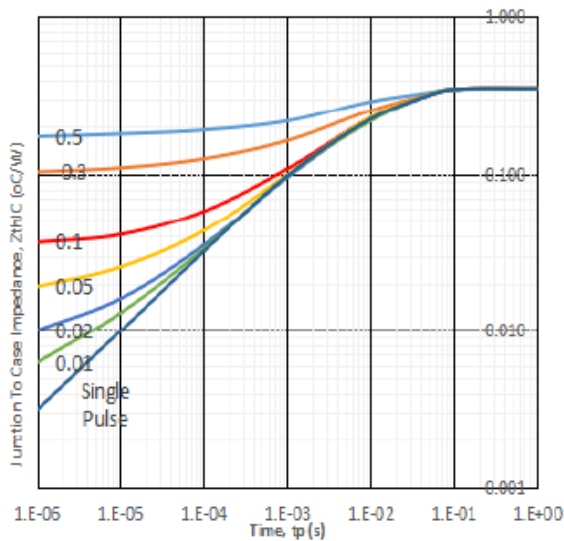
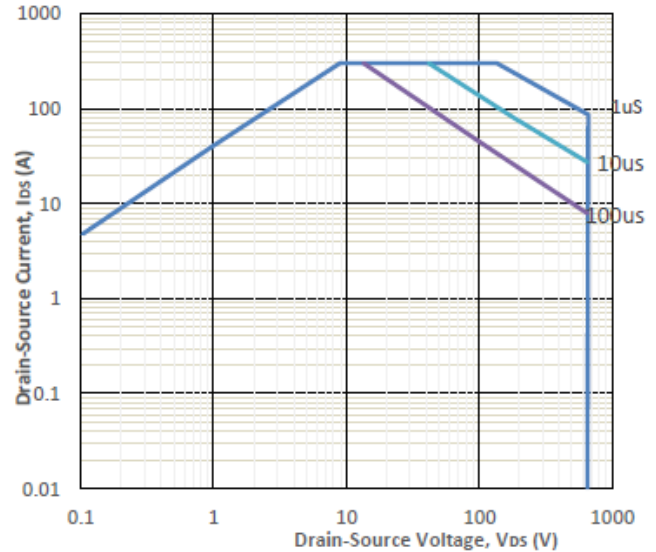
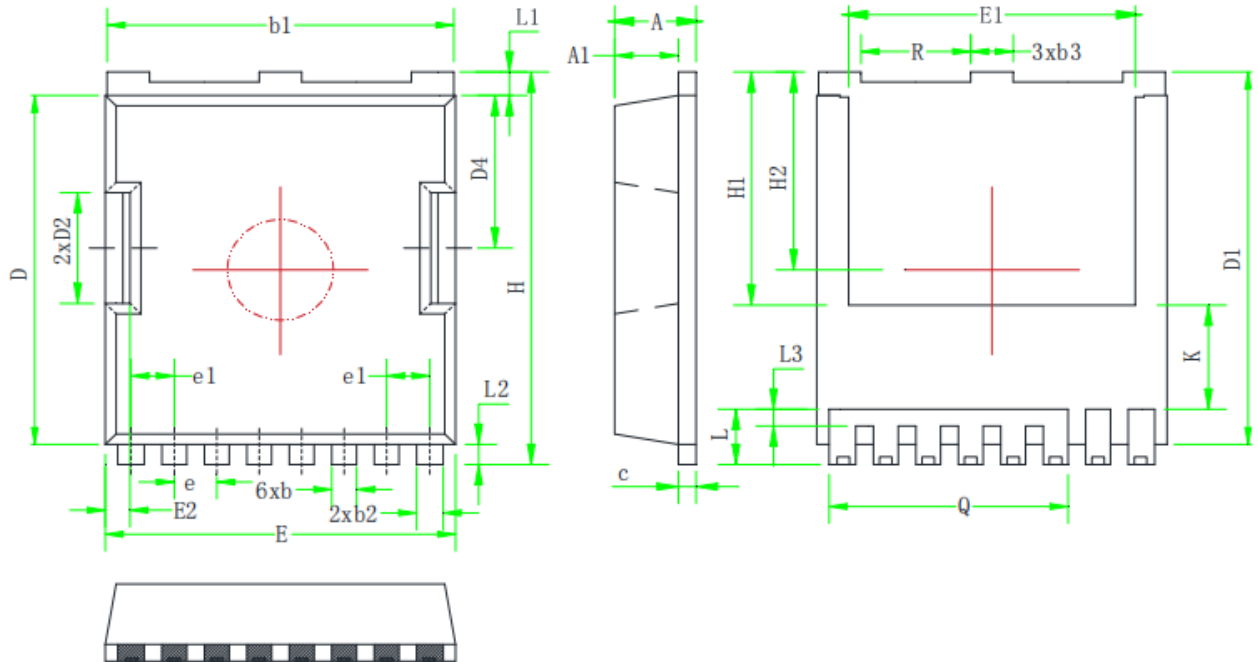


Fig18. Safe Operating Area



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Package Drawing



Dimensions (Unit: mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.25	2.30	2.35	E	9.85	9.90	9.95
A1	1.75	1.80	1.85	E1	8.00	8.10	8.20
b	0.65	0.70	0.75	E2	0.65	0.70	0.75
b1	9.75	9.80	9.90	H	11.60	11.70	11.80
b2	0.70	0.75	0.80	H1	6.95 BSC		
b3	1.15	1.20	1.25	H2	5.90 BSC		
c	0.45	0.50	0.55	K	3.10 REF		
D	10.35	10.40	10.45	L	1.55	1.65	1.75
D1	11.00	11.10	11.20	L1	0.65	0.70	0.75
D2	3.25	3.30	3.35	L2	0.50	0.60	0.70
D4	4.50	4.55	4.60	L3	0.40	0.50	0.60
e	1.20 BSC			Q	6.75 REF		
e1	1.225 BSC			R	3.00	3.10	3.20

Revision version	Description	Date
1	Initial	10.2024